



Qoltec Thermal Putty | 8 W/m-K | 10g | Pink

Product code: 52782

A thermal compound with a thermal conductivity of 8 W/m-K facilitates effective heat dissipation between a heating component and a heat sink. It is suitable for use with, amongst other things, processors, integrated circuits, electronic modules and other components requiring improved heat transfer. The material does not conduct electricity



FOR ELECTRONIC COMPONENTS REQUIRING EFFECTIVE COOLING



Effective heat dissipation and precise surface filling

Qoltec Thermal Putty 8 W/m-K is a thermally conductive compound designed to improve heat transfer between heat-generating electronic components and cooling elements. Thanks to its dense, malleable consistency, it conforms precisely to surfaces and fills minor irregularities and gaps, minimising the formation of air pockets that hinder heat dissipation.

Thermal conductivity of 8 W/m-K

A thermal conductivity of 8 W/m-K facilitates the efficient transfer of heat to a heat sink or other component of the cooling system. The compound can be used with electronic components requiring improved thermal contact, including integrated circuits, memory modules, power supply sections and other heat-generating components.

BETTER THERMAL CONTACT BETWEEN THE COMPONENT AND THE HEAT SINK

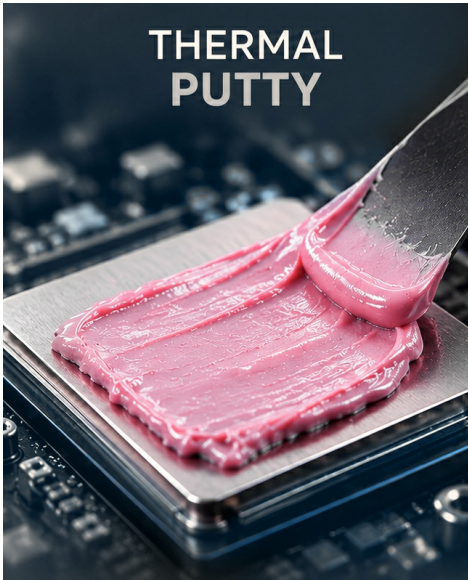


High thermal conductivity, excellent insulation and easy application

Qoltec thermal paste is a top-quality product that offers:

- **high thermal conductivity of 8 W/m K**, ensuring effective heat dissipation,
- **enhanced heat transfer between the component and the heat sink**,
- **high quality**: the paste's properties do not deteriorate over time, ensuring stable performance for years to come,
- **thick, malleable consistency, easy to apply**, allowing you to precisely fill all micro-gaps between individual components,
- **yield**: net weight 10 g,

THICK CONSISTENCY, PRECISE FILLING OF GAPS



The malleable consistency of Thermal Putty

Unlike traditional thin thermal paste, Thermal Putty has a thick and mouldable texture, allowing it to fill larger gaps between the component being cooled and the heat sink. It allows the layer of material to be precisely moulded to the shape of the surface and makes application easier in hard-to-reach areas.

10 g of product for servicing and technical applications

The pack contains 10 g of pink thermal paste, making the product suitable for both one-off repairs and more frequent servicing tasks. It is a practical solution for computer repair shops, electronics technicians and users involved in the maintenance and upgrading of equipment.

CONFIDENCE CONFIRMED BY A WARRANTY



This product comes with a 24-month warranty
Do you want to be sure of the high quality of the product you're buying? **Our solutions will meet your expectations** . Each of the thermal pastes we offer comes with a 24-month warranty valid from the date of purchase.

TECHNICAL DATA

Producer	Qoltec
Thermal conductivity	8 W / m·K
Thermal resistance	0,018 C in / W
Specific gravity	3,0–3,3
Dielectric constants	3,0 at 1 MHz
Additional information	Loss on drying after 96 hours at 100 C: 0.005% Density: 3.1–3.2 g / ml Dielectric strength: 2,0 kV / mm Shelf life: 5 years Odour: Odourless
OTHER PARAMETERS	
Colour	Pink
Operating temperature	–20°C ~ +50°C
Dimensions (D/L x W x H)	32 x 32 x 33 mm
Package	Plastic container
Package contents	1 x Thermal putty 10g
Package depth / length [mm]	32
Package width [mm]	32
Package height [mm]	33
Net weight [kg]	0.10
Gross weight [kg]	0.22
Warranty	24 month
EAN code	5901878527826